

LEXAN™ COPOLYMER HFD1413

REGION ASIA

DESCRIPTION

11 MFR LEXAN High Flow Ductile Copolymer

TYPICAL PROPERTY VALUES

Revision 20180905

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL			
Tensile Stress, yld, Type I, 50 mm/min	58	MPa	ASTM D 638
Tensile Stress, brk, Type I, 50 mm/min	67	MPa	ASTM D 638
Tensile Strain, yld, Type I, 50 mm/min	6	%	ASTM D 638
Tensile Strain, brk, Type I, 50 mm/min	137	%	ASTM D 638
Tensile Modulus, 5 mm/min	2240	MPa	ASTM D 638
Flexural Stress, yld, 1.3 mm/min, 50 mm span	98	MPa	ASTM D 790
Flexural Modulus, 1.3 mm/min, 50 mm span	2230	MPa	ASTM D 790
Hardness, Rockwell R	120	-	ASTM D 785
Tensile Stress, yield, 50 mm/min	61	MPa	ISO 527
Tensile Stress, break, 50 mm/min	68	MPa	ISO 527
Tensile Strain, yield, 50 mm/min	6	%	ISO 527
Tensile Strain, break, 50 mm/min	126	%	ISO 527
Tensile Modulus, 1 mm/min	2120	MPa	ISO 527
Flexural Stress, yield, 2 mm/min	90	MPa	ISO 178
Flexural Modulus, 2 mm/min	2090	MPa	ISO 178
IMPACT			
Izod Impact, notched, 23°C	903	J/m	ASTM D 256
Izod Impact, notched, -20°C	859	J/m	ASTM D 256
Izod Impact, notched, -30°C	435	J/m	ASTM D 256
Multiaxial Impact	120	J	ISO 6603
Instrumented Impact Total Energy, 23°C	77	J	ASTM D 3763
Izod Impact, unnotched 80*10*3 +23°C	NB	kJ/m ²	ISO 180/1U
Izod Impact, unnotched 80*10*3 -30°C	NB	kJ/m ²	ISO 180/1U
Izod Impact, notched 80*10*3 +23°C	70	kJ/m ²	ISO 180/1A
Izod Impact, notched 80*10*3 -30°C	32	kJ/m ²	ISO 180/1A
Charpy 23°C, V-notch Edgew 80*10*3 sp=62mm	80	kJ/m ²	ISO 179/1eA
Charpy -30°C, V-notch Edgew 80*10*3 sp=62mm	43	kJ/m ²	ISO 179/1eA
Charpy 23°C, Unnotch Edgew 80*10*3 sp=62mm	NB	kJ/m ²	ISO 179/1eU
Charpy -30°C, Unnotch Edgew 80*10*3 sp=62mm	NB	kJ/m ²	ISO 179/1eU
THERMAL			
Vicat Softening Temp, Rate B/50	136	°C	ASTM D 1525
HDT, 0.45 MPa, 3.2 mm, unannealed	124	°C	ASTM D 648
HDT, 1.82 MPa, 3.2mm, unannealed	114	°C	ASTM D 648
CTE, -40°C to 40°C, flow	8.E-05	1/°C	ASTM E 831
CTE, -40°C to 40°C, xflow	8.E-05	1/°C	ASTM E 831

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CTE, -40°C to 40°C, flow	8.E-05	1/°C	ISO 11359-2
CTE, -40°C to 40°C, xflow	8.E-05	1/°C	ISO 11359-2
Ball Pressure Test, 125°C +/- 2°C	PASS	-	IEC 60695-10-2
Vicat Softening Temp, Rate B/50	130	°C	ISO 306
Vicat Softening Temp, Rate B/120	131	°C	ISO 306
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	115	°C	ISO 75/Af
PHYSICAL			
Specific Gravity	1.2	-	ASTM D 792
Density	1.2	g/cm ³	ASTM D 792
Mold Shrinkage, flow, 3.2 mm	0.5 – 0.7	%	SABIC method
Melt Flow Rate, 300°C/1.2 kgf	11	g/10 min	ASTM D 1238
Density	1.2	g/cm ³	ISO 1183
Water Absorption, (23°C/sat)	0.3	%	ISO 62
Moisture Absorption (23°C / 50% RH)	0.15	%	ISO 62
Melt Volume Rate, MVR at 300°C/1.2 kg	10	cm ³ /10 min	ISO 1133
OPTICAL			
Light Transmission, 2.54 mm	88	%	ASTM D 1003
Haze, 2.54 mm	<1	%	ASTM D 1003
Refractive Index	1.582	-	ASTM D542
INJECTION MOLDING			
Drying Temperature	105 – 110	°C	
Drying Time	3 – 4	hrs	
Drying Time (Cumulative)	24	hrs	
Melt Temperature	260 – 305	°C	
Nozzle Temperature	255 – 300	°C	
Front - Zone 3 Temperature	260 – 305	°C	
Middle - Zone 2 Temperature	250 – 295	°C	
Rear - Zone 1 Temperature	240 – 280	°C	
Mold Temperature	50 – 80	°C	
Back Pressure	0.3 – 0.7	MPa	
Screw Speed	35 – 75	rpm	
Shot to Cylinder Size	40 – 60	%	
Vent Depth	0.038 – 0.076	mm	

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